



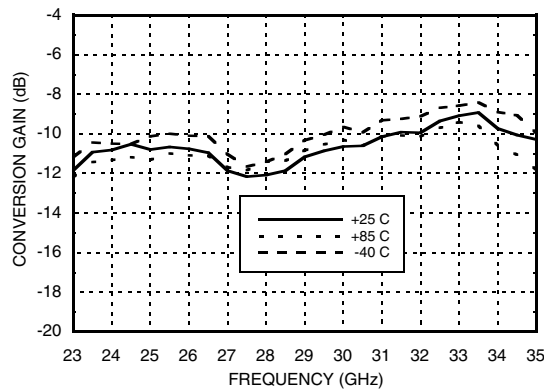
NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED



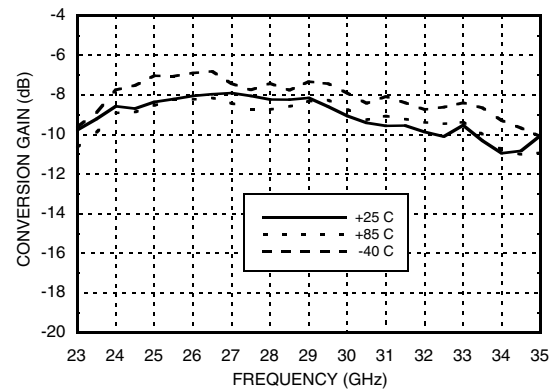
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GaAs MMIC SUB-HARMONIC SMT MIXER, 24 - 34 GHz

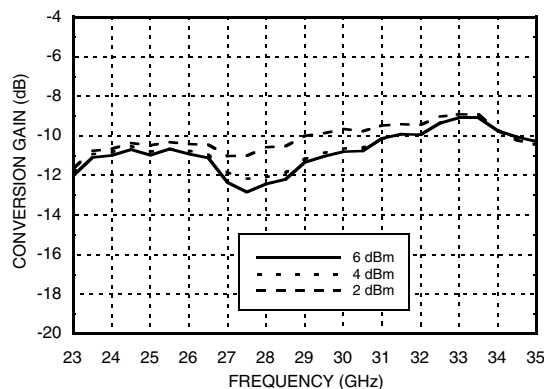
Conversion Gain vs. Temperature, LSB



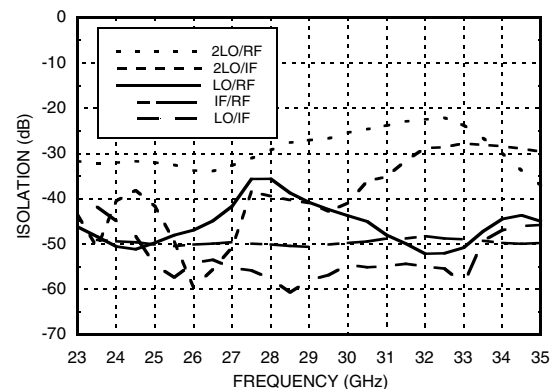
Conversion Gain vs. Temperature, USB



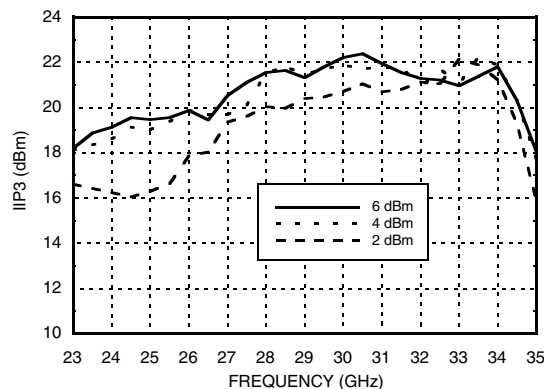
Conversion Gain vs. LO Drive, LSB



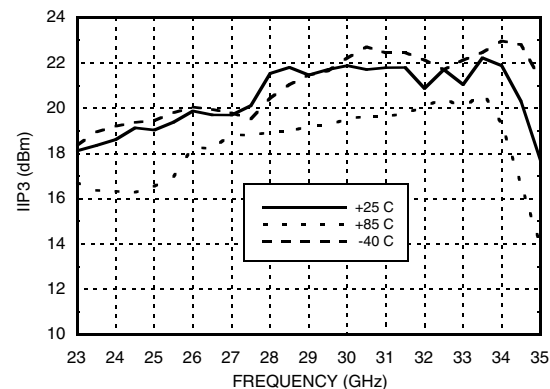
Isolations

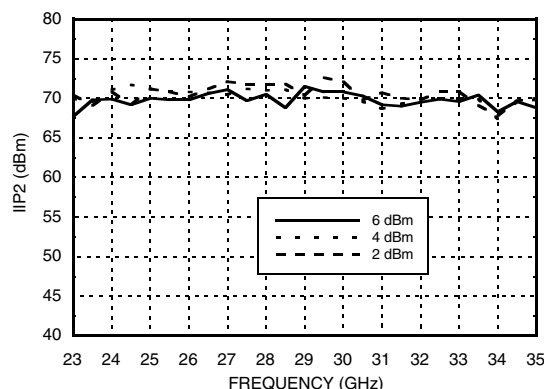
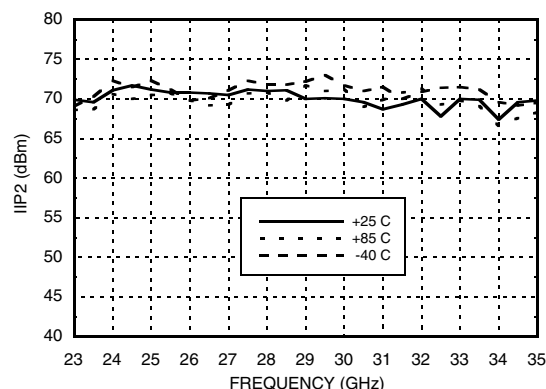
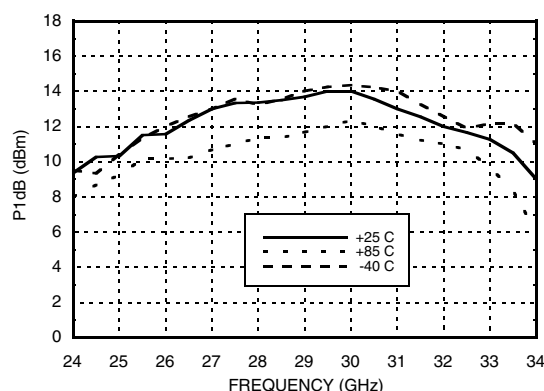
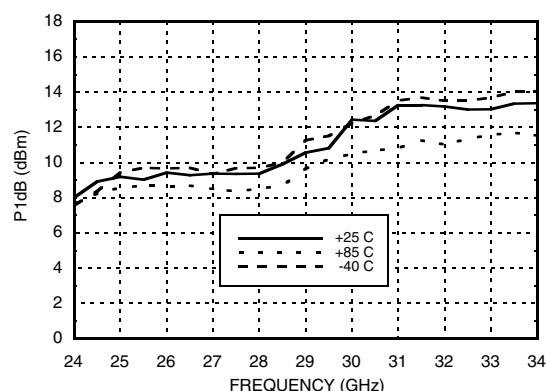
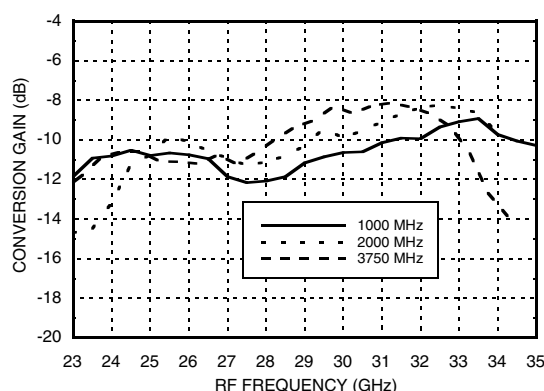
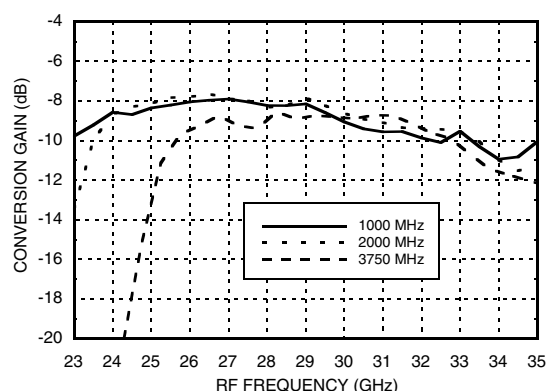


Input IP3 vs. LO Drive



Input IP3 vs. Temperature

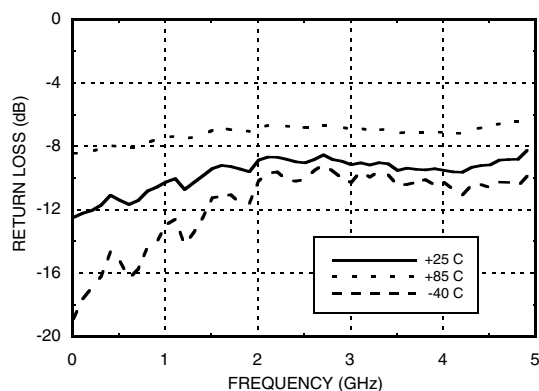


**GaAs MMIC SUB-HARMONIC
SMT MIXER, 24 - 34 GHz**
Input IP2 vs. LO Drive

Input IP2 vs. Temperature

Input P1dB vs. Temperature, LSB

Input P1dB vs. Temperature, USB

Conversion Gain vs. IF Frequency, LSB

Conversion Gain vs. IF Frequency, USB


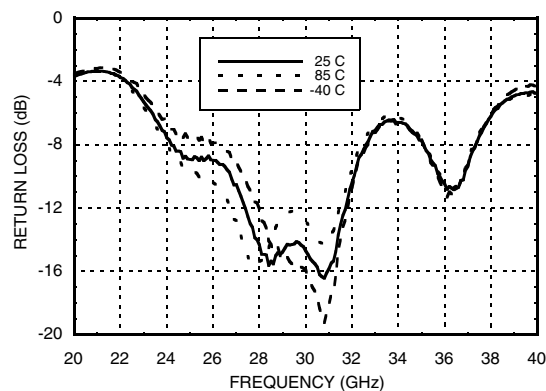
* Two-tone input power = 0 dBm each tone, 1 MHz spacing.

GaAs MMIC SUB-HARMONIC SMT MIXER, 24 - 34 GHz

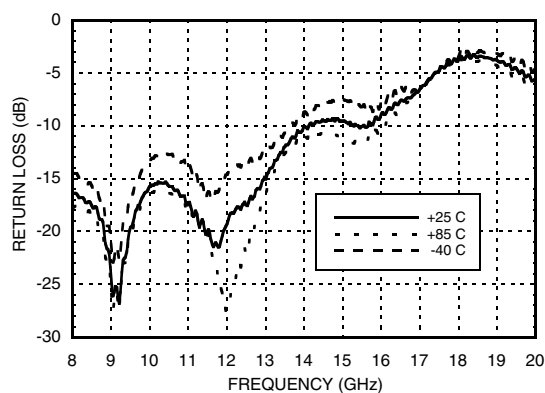
IF Return Loss



RF Return Loss



LO Return Loss



**MxN Spurious Outputs
@ RF Port, Vdd = 5V**

	nLO		
mIF	2	1	0
-3	68		
-2	53	71	66
-1	0	49	32
0	1	31	
1	1	45	31
2	54	66	65
3	66		

IF = 2 GHz @ -10 dBm
 LO = 15 GHz @ 4 dBm
 All values in dBc below IF power level (2LO - 1IF)
 Measured as upconverter



MICROWAVE CORPORATION v04.0614



HMC798LC4

GaAs MMIC SUB-HARMONIC SMT MIXER, 24 - 34 GHz

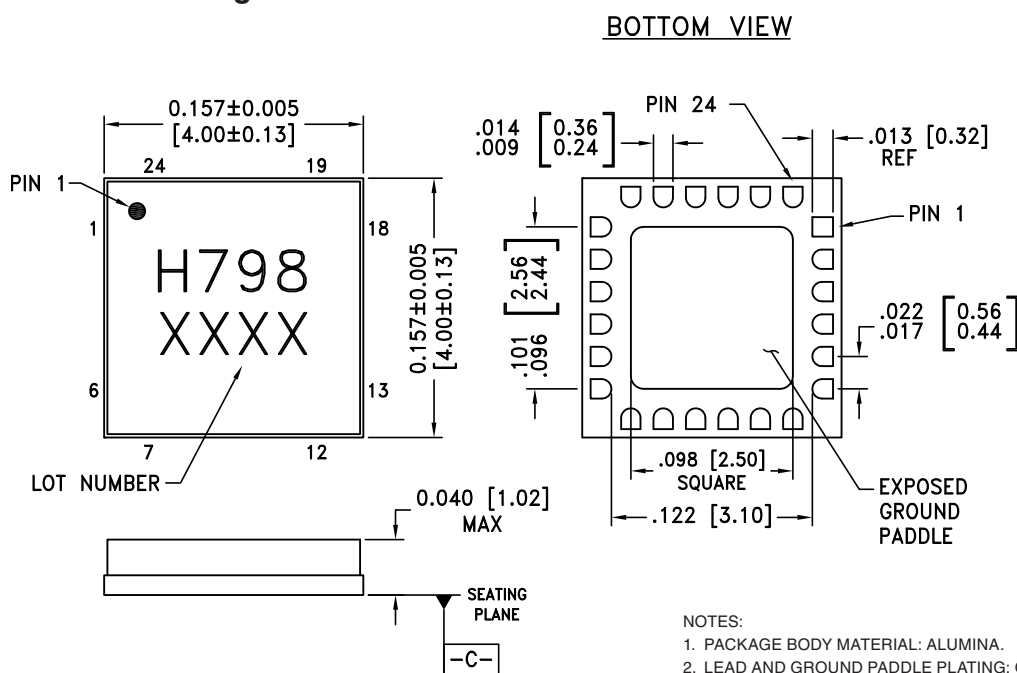
Absolute Maximum Ratings

RF / IF Input (Vdd = +5V)	+13 dBm
LO Drive (Vdd = +5V)	+10 dBm
Vdd	5.5V
Channel Temperature	175 °C
Continuous P _{diss} (Ta = 85 °C) (derate 8.33 mW/°C above 85 °C)	0.75 mW
Thermal Resistance (junction to ground paddle)	119 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing



NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA.
2. LEAD AND GROUND PADDLE PLATING: GOLD FLASH OVER NICKEL.
3. DIMENSIONS ARE IN INCHES (MILLIMETERS).
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
5. CHARACTERS TO BE HELVETICA MEDIUM, .025 HIGH, BLACK INK, OR LASER MARK LOCATED APPROX. AS SHOWN.
6. PACKAGE WARP SHALL NOT EXCEED 0.05MM DATUM -C-
7. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[2]
HMC798LC4	Alumina, White	Gold over Nickel	MSL3 ^[1]	H798 XXXX

[1] Max peak reflow temperature of 260 °C

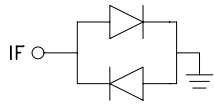
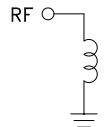
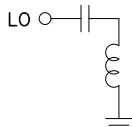
[2] 4-Digit lot number XXXX

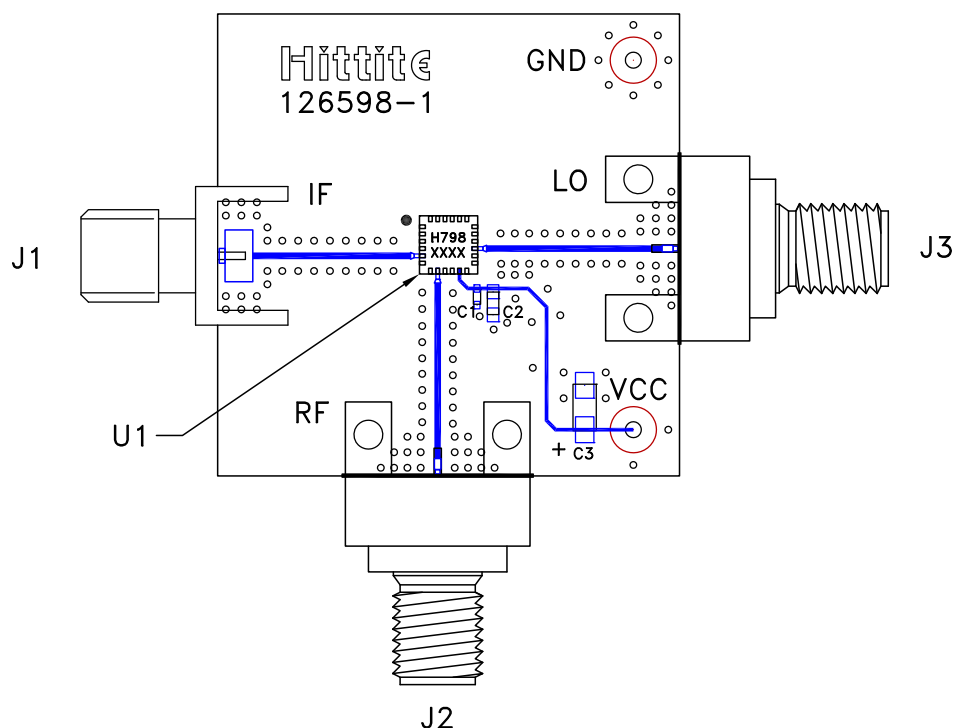
For price, delivery and to place orders: Hittite Microwave Corporation, 2 Elizabeth Drive, Chelmsford, MA 01824

Phone: 978-250-3343 Fax: 978-250-3373 Order On-line at www.hittite.com

Application Support: Phone: 978-250-3343 or apps@hittite.com

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 4, 6, 7, 9, 12 - 14, 16, 18, 19, 24	GND	These pins and package bottom must be connected to RF/DC ground.	
2, 3, 10, 17, 20 - 23	N/C	No connection required. The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
5	IF	This pin is DC coupled and should be DC blocked externally using a series capacitor whose value has been chosen to pass the necessary IF frequency range. Any applied DC voltage to this pin will result in die non-function and possible die failure.	
8	RF	This pin is DC coupled and matched to 50 Ohms.	
11	Vcc	Power supply for the LO Amplifier.	
15	LO	This pin is DC blocked and matched to 50 Ohms.	

Evaluation PCB

List of Materials for Evaluation PCB 126601 ^[1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
J2, J3	PCB Mount SRI K Connector
J4, J5	DC Pin
C1	100 pF Capacitor, 0402 Pkg.
C2	10,000 pF Capacitor, 0603 Pkg.
C3	4.7 μ F Tantalum Capacitor, Case A
U1	HMC798LC4 Mixer
PCB ^[2]	126598 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Arlon 25FR or Rogers 4350

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.



MICROWAVE CORPORATION

v04.0614



HMC798LC4

**GaAs MMIC SUB-HARMONIC
SMT MIXER, 24 - 34 GHz**

Notes:

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

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- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
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- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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www.lifeelectronics.ru